

X-FAB Product Declaration of Non-Use of Banned Substances

In line with the Environmental, Health and Safety Policy of X-FAB, we are working continuously on the reduction of environmental impact via legal compliances.

It is X-FAB's policy, that all purchased materials shall satisfy current government and safety constraints on restricted, toxic and hazardous materials; as well as environmental, electrical and electromagnetic considerations applicable to the country of manufacture and sale.

Restriction of Hazardous Substances (RoHS)

X-FAB hereby confirms that all its goods and materials supplied to its customers and/or its subsidiaries do not contain "intentionally introduced" :

- a. Lead, cadmium, mercury, hexavalent chromium, polybrominated biphenyls (PBB) or polybrominated diphenyl ethers (PBDE) as defined in the Restrictions on Hazardous Substances (RoHS) EU Directives 2002/95/EC unless exempted by regulation.
- b. Flame Retardants as listed under the Annex

X-FAB further warrants that any unintentional contaminant concentrations of these substances are :

- a. Below 0.1% for lead, mercury, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE) for each homogenous material
- b. Impurities of cadmium are less than 0.01% for each homogenous material

Registration, Evaluation, Authorisation and restriction of Chemicals (REACH)

All products produced by X-FAB are classified as Articles and therefore will not need registration under REACH.

X-FAB hereby confirms that all its goods and materials supplied to its customers and/or its subsidiaries, do not contain any substances in the List of Substances of Very High Concern (SVHC).

X-FAB also confirms that its products do not contain any of the substances mentioned in Annex XVII of REACH regulation.

Dr. Manfred Riemer

COO, Group Responsible for EHS
Manfred.Riemer@xfab.com

12 December 2008

About X-FAB

X-FAB is the leading analog/mixed-signal foundry group manufacturing silicon wafers for analog-digital integrated circuits (mixed-signal ICs). X-FAB maintains wafer production facilities in Erfurt and Dresden (Germany), Plymouth (UK), Lubbock, Texas (US) and Kuching, Sarawak (Malaysia), and employs approximately 2,600 people worldwide. Wafers are manufactured based on ultra-modern modular CMOS and BiCMOS processes with technologies ranging from 1.0 to 0.18 micrometers, for applications primarily in the automotive, communications, consumer and industrial sectors. For more information, please visit www.xfab.com.

X-FAB EHS Contacts

Manfred Riemer

Chief Operating Officer

Tel : + 49 361 427 6386

Email : manfred.riemer@xfab.com

Rowena Tan

Group EHS Coordinator

Tel : + 60 82 354 970

Email : rowena.tan@xfab.com